

Product Change Notification - KSRA-09NUVS538

Date:

29 Jan 2019

Product Category:

Ethernet PHYs; Others

Affected CPNs:

7

Notification subject:

CCB 2881 Final Notice: Qualification of ASE as a new assembly site for selected Micrel products available in 32L VQFN package using palladium coated copper with gold flash (CuPdAu) bond wire **Notification text:**

Notification tex

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel products available in 32L VQFN package using palladium coated copper with gold flash (CuPdAu) bond wire

Pre Change:

Assembled at TICP using gold (Au) bond wire

Post Change:

Assembled at ASE using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

Impacts to Data Sheet:

None

		hange	Post Change			
Assembly Site		acking Corp CP)	ASE Inc. (ASE)			
Wire material	Au	Ag	CuPdAu			
Die attach material	EN-4	4900	EN-4900			
Molding compound material	G6	31	G631			
Lead frame material	C1	94	C194			

Change Impact:

None.

Reason for Change:

To improve productivity by qualifying ASE as new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 28, 2019 (date code: 1909)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.



Time Table Summary:

	August 2018				Ш (9	January 2019					February 2019				
Workweek	31	32	33	34	35	Դ₀ ⊓ છ♦ઑ ∎	01	02	03	04	05	06	07	08	09
Initial PCN Issue Date				Х											
Qual Report Availability											Х				
Final PCN Issue Date											Х				
Estimated Implementation Date															Х

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

August 22, 2018: Issued initial notification.

January 29, 2019: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on February 28, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-09NUVS538_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8041NL KSZ8041NLI KSZ8041NLI-TR KSZ8041NLJ-TR KSZ8041NL-TR KSZ8041RNL KSZ8041RNLI KSZ8041RNLI-TR KSZ8041RNL-TR SPNY801052-TR SPNY801084-TR SPNY801165 SPNY801165-TR SPNY801167 SPNY801167-TR SPNZ801034-TR SPNZ801035-TR SPNZ801050-TR SPNZ801052-TR SPNZ801059 SPNZ801059-TR SPNZ801084-TR SPNZ801111-TR SPNZ801114-TR SPNZ801115-TR SPNZ801165 SPNZ801165-TR SPNZ801166 SPNZ801166-TR SPNZ801167 SPNZ801167-TR